Attorney Docket No.: TS02-1193 (N1085.90160)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Number: 7,112,504
Serial No.: 10/694,684
Issued: September 26, 2006
Inventor(s): Ping-Yi Hsin et al.

Title: METHOD OF FORMING METAL-INSULATOR-METAL (MIM) CAPACITORS AT

COPPER PROCESS

Attention Certificate of Corrections Branch

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT FOR PTO MISTAKE (37 CFR 1.322)

Dear Sir:

- Attached is Form PTO/SB/44 wherein the errors occurring in the printed patent are noted by column and line number.
- The exact page and line number where the correct language appears in the application file is:

Declaration filed with application on 10/28/2003 and second inventor's name in Official Filing Receipt dated 5/3/2004;

Application Abstract filed 10/28/2003, page 22;

Attorney Docket No.: TS02-1193

(N1085.90160)

Amendment as filed 8/29/2005, page 2; and

Application as filed 10/28/2003, page 13, line 1.

3. Please send the Certificate to:

Name: Steven E. Koffs, Esquire DUANE MORRIS LLP 30 South 17th Street

Philadelphia, Pennsylvania 19103

Respectfully submitted,

Date: □ □ ₩ € 24, 2007

Russell S. Timm, Ph.D. Registration No. 55,677

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Page 1 of 1

UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO.

30 South 17th Street Philadelphia, PA 19103

VA 22313-1450.

: 7,112,504

APPLICATION NO.: 18/894,684
ISSUE DATE September 26, 2006
INVENTOR(S) Ping-Yi Hein and Zin Chein Wei
It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:
(75) Inventors: delete "Zan Chun Wei" and insert therefore Zin Chein Wei
ABSTRACT delete entire abstract and insert:
A method of forming a MiM capacitor, and the resultant MIM capacitor, comprising the following steps. A structure having a metal structure formed thereover is provided. A dielectric layer is formed over the metal structure and a top layer is formed over the metal structure and a top layer is formed over the metal structure and a top layer is formed over the dielectric layer. A capacitance trench is formed through the top layer and into the dielectric layer. Respective bottom electrodes are formed over: the respective bottom electrodes is the bottom of the capacitance dielectric layer is formed over: the respective bottom electrodes: the bottom of the capacitance trench; and the remaining top layer. Respective opposing initial via openings are formed adjacent the capacitance trench. Respective trench openings are formed above, continuous and contiguous with the lower portions of the respective opposing initial via openings and exposing portions of the underlying metal structure to form respective opposing dual damascene openings. Planarized metal portions are formed within: the dual damascene openings; and the capacitance trench to form a top electrode
Column 4, line 25, after "12" insert and bottom electrodes 30', 30". Capacitance trench 25 includes sidewalls 50 formed of remaining portions of capacitance dielectric layer 32",
Column 4, line 57, delete "Prestent" and Insert therefore Present
MAILING ADDRESS OF SENDER (Please do not use customer number below);
Russell S. Timm, Ph.D., Duane Morris LLP

This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to fair tax by the USPTO to processly an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any